

Master Bond EP21LV Low Viscosity Two Component Epoxy

Category: Polymer, Adhesive, Thermoset, Epoxy, Epoxy Adhesive

Material Notes:

Master Bond Polymer System EP21LV is a two component, low viscosity epoxy resin system for high performance bonding, sealing, coating, encapsulation and casting. It is formulated to cure readily at room temperature or more quickly at elevated temperatures. It has a very forgiving one to one mix ratio by weight or volume. In fact, EP21LV has the unusual characteristic of being able to adjust the properties of the cured system by altering the mix ratio. Conforms Title 21, U.S. Code of Federal Regulations, FDA Chapter 1, Section 175.105 for Food Applications.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Master-Bond-EP21LV-Low-Viscosity-Two-Component-Epoxy.php

Physical Properties	Metric	English	Comments
Viscosity	6000 - 8000 cP	6000 - 8000 cP	
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Thermal Properties	Metric	English	Comments	
Maximum Service Temperature, Air	121 °C	250 °F		
Minimum Service Temperature, Air	-51.1 °C	-60.0 °F		

Processing Properties	Metric	English	Comments
Cure Time	60.0 - 120 min	1.00 - 2.00 hour	
	@Temperature 93.3 °C	@Temperature 200 °F	
	1440 - 2880 min	24.0 - 48.0 hour	
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Descriptive Properties	Value	Comments	
Color Code	"A" Clear; "B" Amber		
Mix Ratio By Weight	100/100		
Set-Up Time, minutes	60-90	At Room Temperature	

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